

Docket No.: 4444-0124P

Application No. 10/646,696
Amendment dated May 24, 2006
Reply to Office Action of February 24, 2006

AMENDMENTS TO THE CLAIMS

1. (Currently Amended) An Internet automatic electrical data system, comprising:
a process controller, used to process ~~the an~~ analyzing order for integrated circuit (IC)
packages entrusted by clients;
a working database coupled to said process controller, used to store the IC package
parameters ~~input-inputted~~ by said ~~a client~~ clients;
a condition parameter database coupled to said process controller to provide the condition
parameters relative to the model of the IC package entrusted by said clients;
an electrical simulation and analyzing software used to analyze said IC package
parameters ~~input-inputted~~ by said clients, and said condition parameters provided by said
condition parameter database;
a report form generator coupled to said electrical simulation and analyzing software to
generate ~~the a~~ report form of analyzing ~~result~~ analyzed results; and
replying means coupled to said report form generator to send said report forms to said
clients.

2. (Currently Amended) ~~A-The~~ system of claim 1, wherein said ~~client transmits~~ clients
transmit said IC package parameters through the Internet.

3. (Currently Amended) ~~A-The~~ system of claim 1, wherein said replying means sends
said report forms to said clients ~~comprises the usage of the an~~ utilizing at least one of electronic
mail and facsimile.

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4. (Currently Amended) ~~A-The~~ system of claim 1, wherein said process controller accesses said condition parameters from said condition parameter database, and then transfers said condition parameters along with said IC package parameters ~~input-inputted~~ by said clients to said electrical simulation and analyzing software.

5. (Currently Amended) ~~A-The~~ system of claim 1, wherein the IC package types provided by said condition parameter database comprise BGA (ball grid array), BCC, QFP, SOP, QFN (quad flat no-lead), Flip Chip, CSP (chip scale package), and WLCSP (wafer level chip scale package).

6. (Currently Amended) ~~A-The~~ system of claim 1, wherein said IC package parameters ~~input-inputted~~ by said clients ~~comprises-comprise~~ the number of I/O (input and output) terminals, package type, substrate layer, substrate thickness, information about lead frame, and frequency.

7. (Currently Amended) ~~A-The~~ system of claim 1, wherein said electrical simulation and analyzing software constructs a three-dimensional model according to said IC package parameters and said condition parameters.

8. (Currently Amended) ~~A-The~~ system of claim 7, wherein said electrical simulation and analyzing software calculates the resistance, inductance and capacitance of said IC package according to said IC package parameters and said condition parameters.

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9. (Currently Amended) ~~A-~~The system of claim 1, wherein said electrical simulation and analyzing software transfers said analyzing result to said report form generator.

10. (Currently Amended) A method for ~~automatic~~ automatically analyzing electrical data through ~~the~~ Internet, ~~which comprises~~ comprising the following steps:

inputting IC package parameters for analyzing by a client;

transferring said IC package parameters to a working database for storing through ~~the~~ Internet;

accessing said IC package parameters from said working database and condition parameters relative to said IC package parameters from a condition parameter database by a process controller;

transferring said IC package parameters and said condition parameters to an electrical simulation and analyzing software for simulating and analyzing by said process controller to generate an analyzed result;

transferring the ~~analyzing~~ analyzed result to a report form generator for generating ~~the a~~ report form of ~~analyzing~~ analyzed result;

~~transferring said report form generator~~ transferring said report form via said report form generator to a replying means; and

sending said report form to said ~~clients~~ client by said replying means.

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11. (Currently Amended) ~~A-~~The method of claim 10, wherein said client transmits said IC package parameters through the Internet.

12. (Cancelled)

13. (Currently Amended) ~~A-~~The method of claim 10, wherein said IC package parameters ~~input-inputted~~ by said client comprises the number of I/O terminals, package type, the number of the substrate layer, substrate thickness, information about lead frame, and frequency.

14. (Currently Amended) ~~A-~~The method of claim 10, wherein said electrical simulation and analyzing software constructs a three-dimensional model according to said IC package parameters and said condition parameters.

15. (Currently Amended) ~~A-~~The method of claim 14, wherein said electrical simulation and analyzing software calculates the resistance, inductance, and capacitance of said IC package according to said IC package parameters and said condition parameters.

16. (Currently Amended) ~~A-~~The method of claim 10, wherein the IC package types provided by said condition parameter database comprise BGA (ball grid array), BCC, QFP, SOP, QFN (quad flat no-lead), Flip Chip, CSP (chip scale package), and WLCSP (wafer level chip scale package).